## Integrated Low Noise Amplifier and Balun for MRI receiver-on-coils

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## Introduction

Future MRI systems and applications are being developed to satisfy the persistent demand for higher image resolution and temporal processing. To satisfy those demands the quantity of elements that comprise an imaging coil must be increased dramatically. It is customary for each receiver coil element to be paired with a low noise amplifier (LNA) and one or more baluns. To maximize performance, the LNA is located in close proximity to the receiver coil element; when the LNA is placed near the receiver coil element, an increase in the density of components and structures in the magnet bore and region of interest results. This increased component density can adversely impact image quality by interference with the flux field. The balun is used to provide for coil element-to-element isolation, and to support optimal image quality. Alternative technologies have been sought that would enable the coils

image quality. Alternative technologies have been sought that would enable the coils to increase the their functional density, i.e., 128 coil elements in the existing receiver coil package volume.

This paper examines the feasibility, benefits, challenges, and risks associated with locating the LNA inside the balun package volume, without degradation of performance and adverse impact on overall image quality. The risks include achieving a high density LNA-Balun package without adverse impact on LNA

performance, difficulty tuning the LNA-Balun, and overheating. **Method** 

A commercially available LNA is used as a basis for comparison for the LNA-Balun circuit thereby reducing evaluation risk. The LNA schematic is divided into sections including input matching, amplification, output matching, protection and balun. The sections of the LNA-Balun are implemented in sections of a copper-on polyimide flex circuit, as shown in Figure 3. Once the flex has been populated with components, it is folded to form a 3D structure that can be assembled into the balun housing.

Power for the LNA is provided through the signal co-axial Figure line. The LNA-Balun was compared to a traditional design shown in Figures 2 and 4.

## Results

The LNA-balun was fabricated, assembled, and tested yielding the following results:

|                                 | <b>S-Parameter</b> | Measured Value             |
|---------------------------------|--------------------|----------------------------|
| Input impedance                 | $(S_{11})$         | $Z_{in} = 2.78\Omega$      |
| Amplifier Stability             | $(S_{12})$         | < -51dB                    |
| Amplifier Gain                  | $(S_{21})$         | =26.7db                    |
| Output impedance                | $(S_{22})$         | $Z_{out} = 57.9\Omega$     |
| Noise Figure                    |                    | =0.91dB                    |
| Dynamic range (1dB compression) |                    | =12.7dBm                   |
| Output linearity                |                    | OIP3 = 19dBm               |
| Balun Impedance                 |                    | $Z_{balun} = 2.2 k \Omega$ |
|                                 |                    |                            |

## Discussion

An integrated LNA-Balun has been demonstrated its performance verified. A 60% volume reduction has been achieved compared to the individual LNA and balun configuration. The integrated LNA-Balun utilizes commercial electronic packaging technology and manufacturing methods.

Figure 3 LNA-Balun Flex Assembly



Figure 1 Traditional Balun



Figure 2: Single Channel Receiver Coil



Figure 4 LNA-Balun Receiver



Figure 5 Integrated LNA-Balun Prototype

